

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.
Ratio 6
6921 RW Duiven
The Netherlands

PRESS RELEASE

BE Semiconductor Industries Announces Packaging and RFID Die Bonding Equipment Orders

Duiven, the Netherlands, October 22, 2007, BE Semiconductor Industries N.V. ("the Company" or "Besi") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced the receipt of orders in October 2007 aggregating approximately € 4.3 million for packaging and die bonding equipment.

The Company's Fico subsidiary received an order of approximately € 2.8 million for four AMS-I molding systems and two Compact Line trim and form systems from a leading Chinese semiconductor manufacturer. The customer intends to utilize Besi's equipment for the packaging of SOT/SOD discrete devices in conventional leadframe process applications as part of their expansion of discrete production capacity. Delivery is scheduled for the first quarter of 2008.

Besi's Datacon subsidiary also received orders recently aggregating € 1.5 million for its 8800 FC ("Flip Chip") Smart Line die bonding system. Datacon's 8800 FC Smart Line system is a fully automated, high-performance production line providing customers a complete Radio Frequency Identification Device ("RFID") chip assembly solution based on a highly cost-effective method of direct chip attach to RFID antennae. The orders were placed by three global smart card manufacturers and are anticipated to be delivered in the fourth quarter of 2007.

Helmut Rutterschmidt, Executive Board member Marketing and Sales of Besi commented, "We are very pleased to receive these important customer orders this month reflecting progress in our penetration of the Chinese packaging equipment market with Fico systems and market acceptance by smart card manufacturers of our Datacon die bonding systems for RFID applications."

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European, Asian, Korean and Japanese semiconductor manufacturers and subcontractors which utilize its products for both array connect and conventional leadframe manufacturing processes. For more information about Besi, please visit our website at www.besi.com.

Caution Concerning Forward Looking Statements

This press release contains forward-looking statements, which are found in various places throughout the press release, including statements relating to expectations of orders, net sales, product shipments, backlog, timing of purchases of assembly equipment by customers and capital expenditures. The words “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward looking statements, although not all forward looking statements contain these identifying words. While these forward looking statements represent our judgments and future expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from our expectations. These factors include, but are not limited to, those listed or discussed in Besi’s Annual Report for the year ended December 31, 2006, as well as the risk that anticipated orders may not materialize or that orders received may be postponed or canceled, generally without charges; the volatility in the demand for semiconductors and our products and services; acts of terrorism and violence; overall global economic conditions; risks, such as changes in trade regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations; potential instability in foreign capital markets; the risk of failure to successfully manage our expanding and more diverse operations; and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We are under no obligation to (and expressly disclaim any such obligation to) update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

Contacts:

Richard W. Blickman
President & CEO
Tel. (31) 26 319 4500
investor.relations@besi.nl

Cor te Hennepe
Director of Finance
Tel. (31) 26 319 4500
investor.relations@besi.nl

BE SEMICONDUCTOR INDUSTRIES N.V.
Ratio 6
6921 RW Duiven

PERSBERICHT

BE Semiconductor Industries kondigt orders aan voor packaging en RFID die bonding machines

Duiven, 22 oktober 2007, BE Semiconductor Industries N.V. ("Besim") (Euronext: BESI), een toonaangevende leverancier van machines voor de assemblage van halfgeleiders maakt melding van de ontvangst in oktober 2007 van orders voor een totaalbedrag van ca. € 4,3 mio voor packaging en die bonding machines.

Besim dochter Fico heeft een order ontvangen van een Chinese halfgeleiderproducent voor vier AMS-I molding machines en twee "trim en form" Compact Line machines. Deze machines worden door de klant toegepast voor bepaalde discrete halfgeleiderproducten SOT/SOD in conventionele leadframe technologie. Levering is gepland in het eerste kwartaal 2008.

Tevens heeft Besim dochter Datacon drie orders ontvangen voor een 8800 FC (Flip Chip) Smart Line die bonding machine. De Datacon 8800 FC Smart Line is een volledig geautomatiseerde "high performance" productielijn voor Radio Frequency Identification Device ("RFID") chipmontage op basis van een rechtstreeks montageprincipe in RFID antennes. Levering is gepland in het vierde kwartaal 2007.

Helmut Rutterschmidt, Raad van Bestuur lid Marketing & Sales Besim: "Wij zijn zeer verheugd met deze belangrijke orders, die wij in oktober hebben ontvangen, welke enerzijds het succes laten zien van de positie van Fico packaging machines in China en anderzijds de verdere marktverovering van Datacon met die bonding machines voor RFID."

Contactpersonen:

Richard Blickman
President & CEO
Tel. 026-3194500

Cor te Hennepe
Director of Finance
Tel. 026-3194500